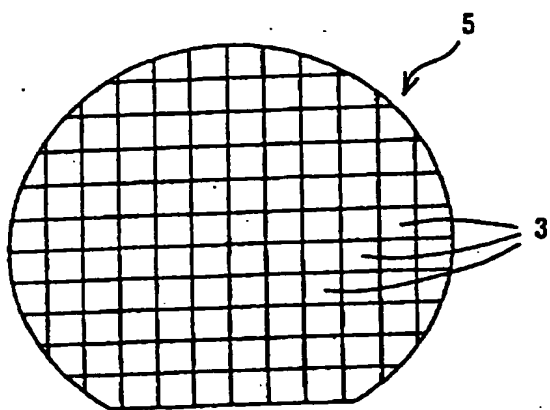
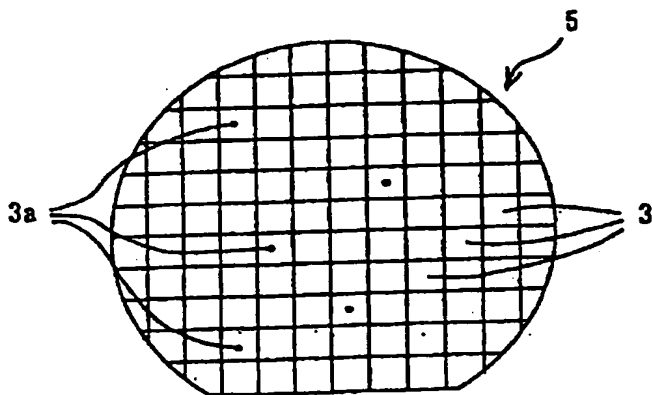


**Fig. 1**



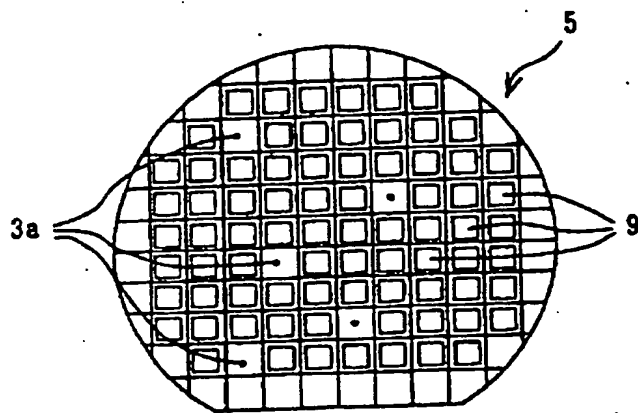
**3: Semiconductor chip forming section**  
**5: Semiconductor wafer**

**Fig. 2**



**3a: "BAD" mark**

**Fig. 3**

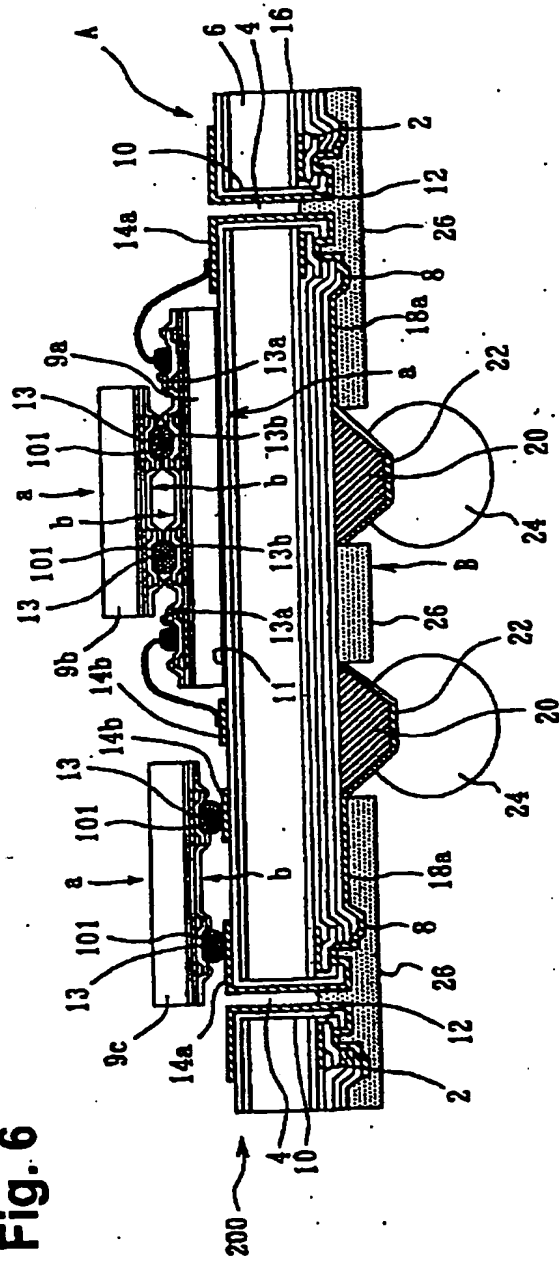


**9: Segmented other semiconductor chips**



## 100: Semiconductor device

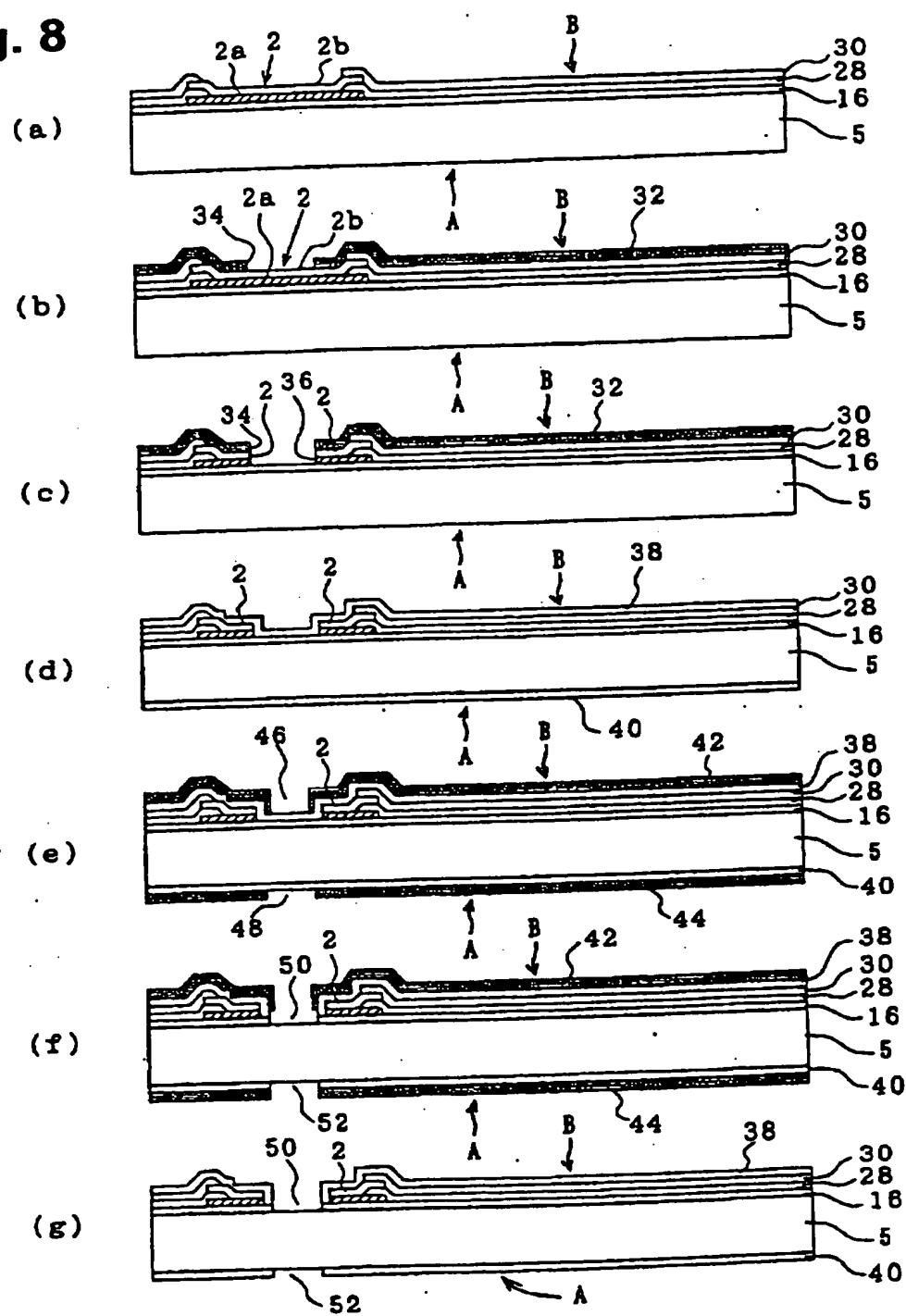
**Fig. 6**



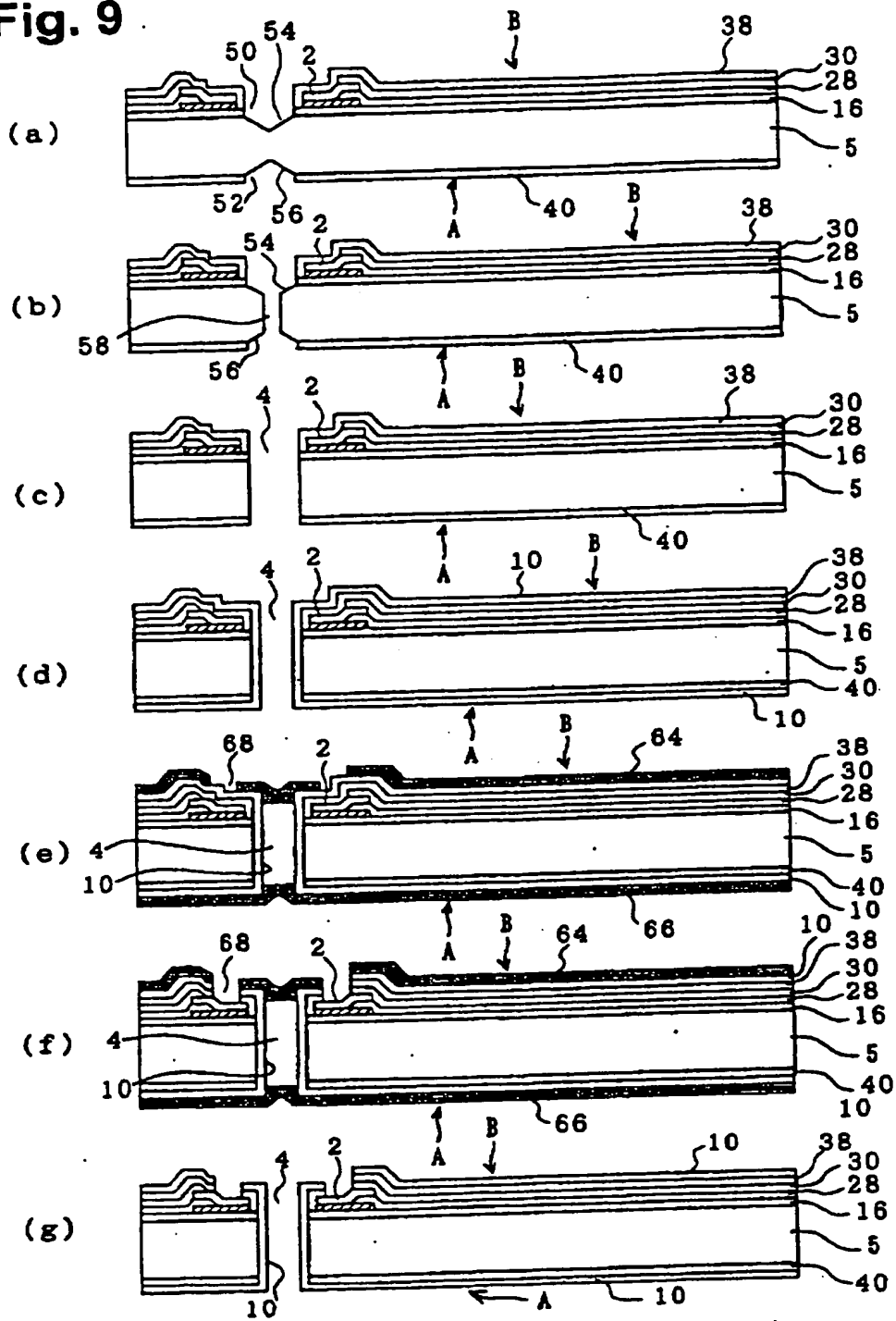
9a, 9b, 9c : Segmented other semiconductor chips  
200 : Semiconductor device

**6b: Segmented another semiconductor chip**  
**300 : Semiconductor device**

**Fig. 8**

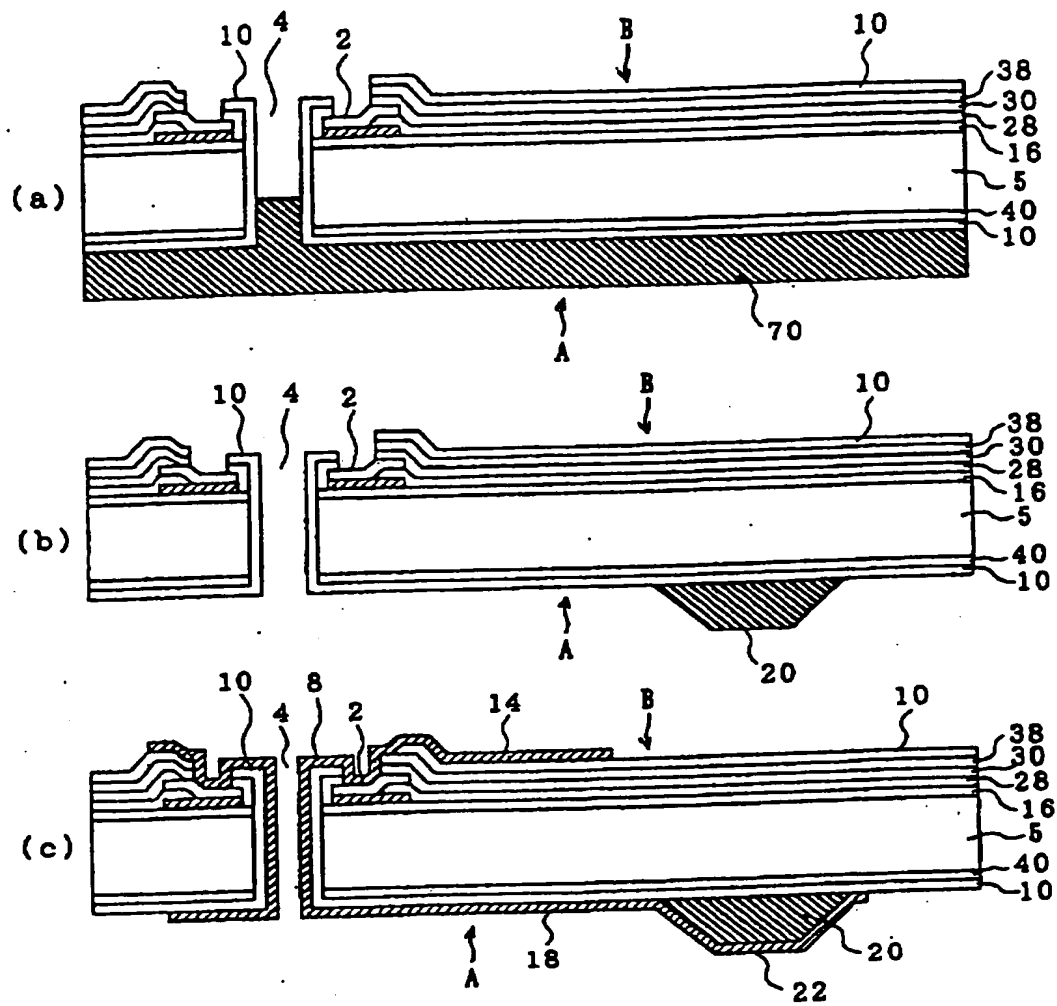


**Fig. 9**





**Fig. 10**



**Fig. 11**

